

**Amendments to the Claims:**

The following listing replaces all prior listing of claims in the application.

**Listing of Claims**

1. (Currently amended) A lithographic method comprising the pressing of a substrate, the method comprising:

preparing a substrate surface by forming a composite layer on the substrate, wherein forming the composite layer comprises forming an internal sub-layer of curable material in contact with the substrate surface and curing the internal sub-layer, and forming an external sub-layer adjacent to the cured internal sub-layer;

pressing a mold comprising a pattern of recesses and protrusions, wherein the protrusions of the mold penetrate into the external sub-layer until the protrusions contact the internal sub-layer;

performing at least one etching process in which the composite layer is etched by removing the internal sub-layer in regions defined by recesses formed in the external sub-layer until portions of a surface of the substrate have been exposed; and

etching portions of the substrate exposed by the recesses using an etching pattern defined by the mold pattern

2. (Cancelled)

3. (Previously presented) The method according to claim 1, wherein forming the internal sub-layer and the external sub-layer comprise forming the same material.

4. (Previously presented) The method according to claim 1, wherein curing the internal sub-layer comprises heating the internal sub-layer at a temperature higher than a curing temperature of the internal sub-layer, and wherein pressing the mold comprises pressing at a pressing temperature higher than a glass transition temperature of the external sub-layer.

5. (Previously presented) The method according to claim 1, wherein forming the internal sub-layer of a curable material comprises forming a polymer.

6. (Previously presented) The method according to claim 1, wherein forming the internal sub-layer of a curable material comprises forming a resin configured to be cross-linked.

7. (Previously presented) The method according to claim 5, wherein forming the internal sub-layer of a curable material comprises forming one of a negative resin or a positive resin.

8. (Previously presented) The method according to claim 1, wherein forming the internal sub-layer comprises forming a sub-layer having a thickness of 0.01 micron to 1 micron.

9. (Previously presented) The method according to claim 1, wherein forming the external sub-layer comprises forming the external sub-layer to a thickness less than a depth of the pattern of recesses.

10. (Previously presented) The method according to claim 6, wherein forming a resin comprises forming one of a negative resin or a positive resin.

11. (Currently amended) A lithographic method comprising:

forming a first layer on-in contact with a surface of a substrate, the first layer comprising a curable material, and curing the first layer;

forming a second layer on the first layer, the second layer comprising a deformable material;

pressing a mold against the second layer, wherein protrusions of the mold form recesses in the second layer that expose portions of the first layer;

etching the exposed portions of the first layer using the second layer as an etch mask, and exposing surface regions of the substrate; and

etching the surface regions of the substrate using at least the first layer as an etching mask.

12. (New) The method according to claim 11, wherein forming a first layer and a second layer comprise forming the same material.